

IN THE SPECIFICATION:

Please replace the Summary of Invention section on page 2, line 27 through page 3, line 17 with the following amended section:

--The present invention has been made in view of the above-described problems of the prior art[[s]], and an object of the present invention is therefore to provide a back side incident type image pickup sensor which is improved in spatial resolution and which is free from the influence of stray light.

In order to attain the above-mentioned object, according to the present invention, there is provided a back side incident type ~~image pickup~~ fingerprint sensor having on the front side of a semiconductor substrate a photoelectric conversion portion and an electric circuit, and having on the back side of the semiconductor substrate an opening through which a light ~~beam~~ containing infrared radiation is ~~let in to be~~ incident, the incident light containing infrared radiation being detected by the photoelectric conversion portion formed on the front side of the semiconductor substrate, wherein a distance, in a direction parallel to the semiconductor substrate, between the electric circuit on the front side of the semiconductor substrate and an edge of the opening on the back side of the semiconductor substrate is 0.303 times the thickness of the semiconductor substrate or more~~in which the electric circuit is placed to keep a given distance in the horizontal direction from the opening.~~--